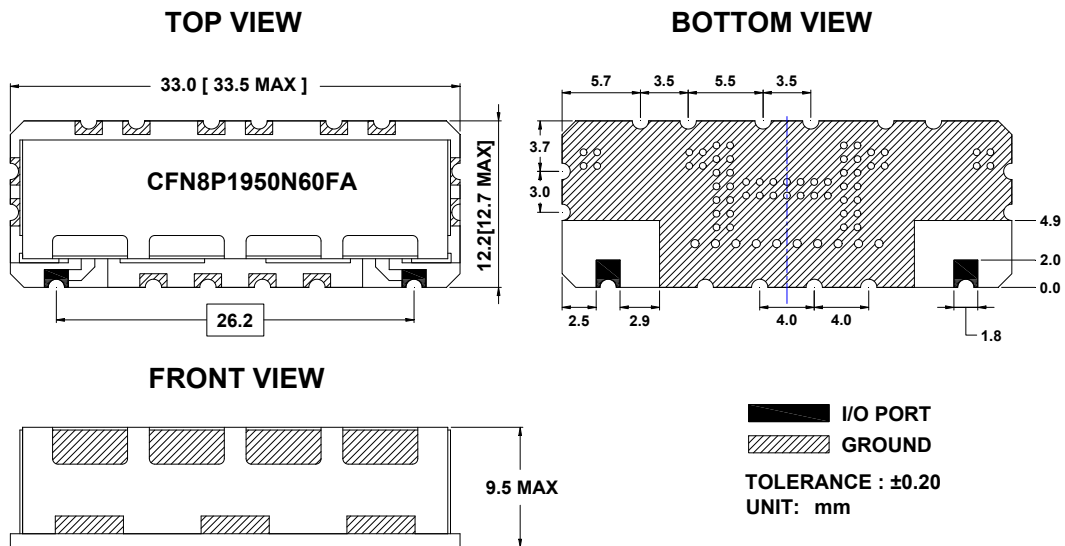


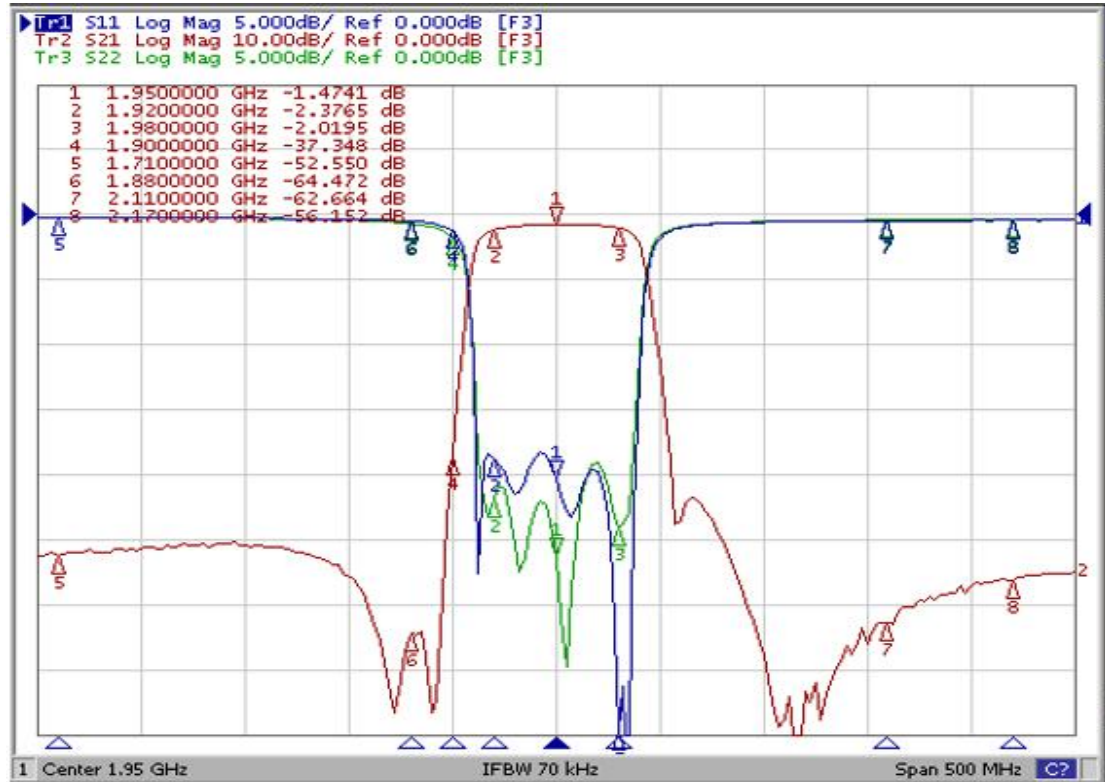
Electrical Specification

ITEMS	SPEC	UNIT
Center Frequency [fo]	1950	MHz
Bandwidth [BW]	fo ±30 [1920 ~ 1980]	MHz
Insertion Loss in BW	2.8	dB max
Ripple in BW	1.2	dB max
Return Loss in BW	18.0	dB min
Attenuation <input checked="" type="checkbox"/> Absolute Value <input type="checkbox"/> Relative Value	33dB min @ fo ± [1900]	MHz
	40dB min @ fo ± [1710]	MHz
	45dB min @ fo ± [1710~1880]	MHz
	50dB min @ fo ± [2110~ 2170]	MHz
Group Delay Variation		ns max
Input Power	2	W max.
In/Out Impedance	50 Ω	
Operation Temperature Range	-40°C to +85°C	

Mechanical Specification

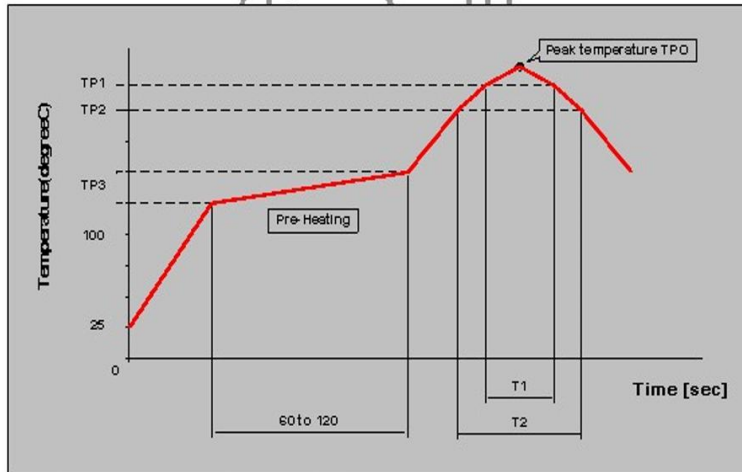


Plot Data



Recommanded PC Board Pattern

 Soldering Condition



Measuring point of temperature : IN-OUT Terminals of The Device

Reflow Soldering : Both Convection and Infrared Rays, Hot Air and Hot Plate

Reflow standard condition	TPO (°C)	TP1 (°C)	T1 (s)	TP2 (°C)	T2 (s)	TP3 (°C)
Sn-3Ag-0.5 solder	245±5	220	30 to 60	—	—	150 to 180
Test condition of reflow heat resistance	260±5/-0	240	20	220	70	150 to 180